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SEMI Honors Developers of Tessera Chip-Scale Packaging Technology

In recognition for contributions to the development and commercialization of Tessera's Micro Ball Grid Array (μ BGA®) technology, SEMI awarded Thomas Di Stefano, John W. Smith, Jr. and Michael Warner the 2010 SEMI Award for North America; the association's highest honor for technical contributions to the semiconductor industry. The award was presented during a banquet at the 2011 SEMI Industry Strategy Symposium (ISS) in Half Moon Bay, California.

"Our industry honors Tom Di Stefano, John Smith and Michael Warner for their combined efforts to commercialize μ BGA® technology while at Tessera Technologies," said Stanley T. Myers, president and CEO of SEMI. "This critical packaging technology was an important development in the proliferation of smaller personal electronic devices that have spurred the market for semiconductor devices."

Di Stefano was the founding president of Tessera Technologies and a co-founder of Chip Scale Review, where he continues to be a regular contributor, and serve on the editorial advisory board. Di Stefano helped build Tessera into a world leader in miniaturized packaging. John W. Smith, Jr. joined Tessera in 1992 as its CEO where he served until his retirement in 2000. Michael Warner, a Tessera Fellow, joined the company in 1994 as the vice president responsible for developing products employing μ BGA solutions for commercial applications.

"The introduction of chip scale packaging by Tessera enabled a decrease in package size and an increase in package frequency while reducing the total power required," said Bill Bottoms, chairman of the SEMI Award Advisory Committee." This innovation is now the packaging solution of choice for most memory devices and a significant number of logic devices. It was initially adapted to meet performance requirements and the high-volume commercialization led to its widespread adoption as a lower- cost packaging alternative."

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